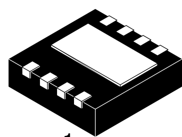
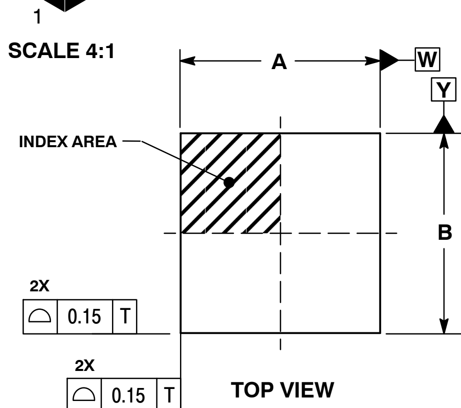
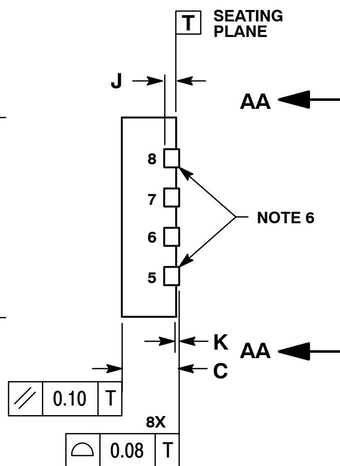


DFN8 3x3, (MICRO8 LEADLESS)

CASE 846C−01
ISSUE D

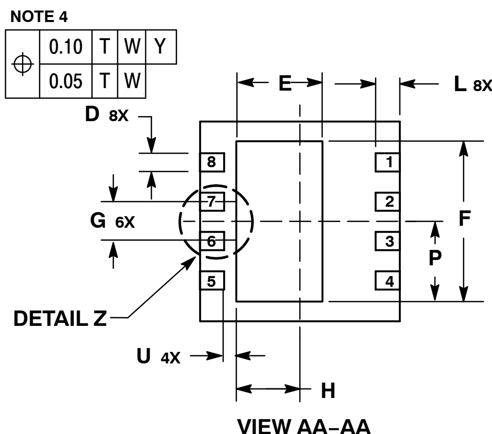
DATE 28 JUN 2010

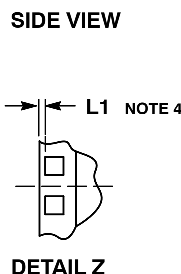




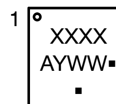
NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95−1 SPP−012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
4. DIMENSION D APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 MM AND 0.30 MM FROM TERMINAL TIP. DIMENSION L1 IS THE TERMINAL PULL BACK FROM PACKAGE EDGE, UP TO 0.1 MM IS ACCEPTABLE. L1 IS OPTIONAL.
5. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
6. OPTIONAL SIDE VIEW CAN SHOW LEADS 5 AND 8 REMOVED.

DIM	MILLIMETERS MIN	MILLIMETERS MAX
A	3.30 BSC	
B	3.30 BSC	
C	0.85	0.95
D	0.25	0.35
E	1.30	1.50
F	2.55	2.75
G	0.65 BSC	
H	0.95	1.15
J	0.25 BSC	
K	0.00	0.05
L	0.35	0.45
L1	0.00	0.10
P	1.28	1.38
U	0.17 TYP	





GENERIC MARKING DIAGRAM*

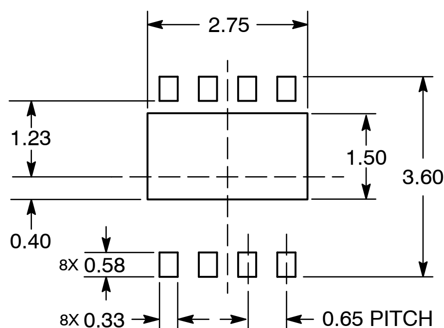


XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DFN8 3X3, (MICRO8 LEADLESS)	PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY A. SAM.	29 MAR 2002
A	REMOVED TIE BARS ON CENTER FLAG. REMOVED DIMENSIONS R AND S. ADJUSTED BOTTOM VIEW AND ISOMETRIC PICTURE ACCORDINGLY. CHANGED DIMENSION D TO 0.25 MM AND 0.35 MM. REQ. BY P. CELAYA.	03 AUG 2005
B	CHANGED SIDE VIEW DRAWING. CHANGED DIMENSIONS A AND B TO BASIC DIMENSIONS. REMOVED DIMENSIONS M AND N. ADDED DIMENSION L1. ADDED NOTE 6. REQ. BY P. CELAYA.	20 SEP 2005
C	CHANGED DIMENSION U TO 0.17 TYP. REQ. BY P. CELAYA.	06 MAR 2006
D	ADMINISTRATIVE CHANGE TO REFLECT THE INITIAL RELEASE OF DOCUMENT. REQ. BY V. ILAS.	28 JUN 2010

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